

**CLAIMS:**

1. An electronic device comprising at least one semiconductor element having a first and an opposed, second side, which at least one semiconductor element is provided with a first, a second and a third bonding pad, and which is encapsulated with a passivating material, further comprising an electrically conductive layer at the first side,
  - 5 - which layer comprises a first, a second and a third contact pad suitable for external contacting, and which first, second and third contact pads are connected to the first, second and third bonding pads respectively through electrically conductive interconnecting means,
  - which first and second contact pads are provided with a first and a second side face and which third contact pad is provided with a first side face,10 which first side faces of the first and second contact pads are facing the first side face of the third contact pad and are separated by a spacing that is continuous along the first side faces,
  - which second side faces of the first and second contact pads are facing each other and comprise a first part and a second part, the first part located nearer to the first side15 face than the second part,
  - which first parts of the second side faces of the first and second contact pads are at a mutual distance that is smaller than the distance between the second parts of these side faces.
- 20 2. An electronic device as claimed in claim 1, characterized in that the first and the second part of the second side faces are oriented substantially parallel to each other and are separated through a third parallel.
3. An electronic device as claimed in claim 1 or 2, characterized in that the first25 and second side faces of the first and the second contact pads enclose an angle which is in between of 90 and 180 degrees.
4. An electronic device as claimed in claim 1,2 or 3, characterized in that the spacing has a trapezium-shape.

5. An electronic device as claimed in claim 1, characterized in that the spacing is straight.

5 6. An electronic device as claimed in claim 1, characterized in that the third contact pad is connected to ground.

7. An electronic device as claimed in claim 1 or 6, characterized in that:

10 - the third contact pad is provided with a second side face opposed to the first side face;

- a fourth and a fifth contact pad are present at the second side face of the third contact pads, which are connected to fourth and fifth bonding pads at the at least one semiconductor element;

15 - the fourth and fifth contact pads are provided with a first and a second side face, which first side faces of the fourth and fifth contact pads are facing the second side face of the third contact pad and are separated by a spacing that is continuous, which second side faces are facing each other and comprise a first part and a second part, the first part located nearer to the first side face than the second part, which first parts of the second side faces are at a mutual distance that is smaller than the distance between the second parts of these side 20 faces.

8. An electronic device as claimed in claim 1 or 6, characterized in that the third contact pad is connected with a second conductive layer, which is present at the second side of the semiconductor element.

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9. An electronic device as claimed in claim 1, characterized in that the semiconductor element is a transistor.

30 10. Use of the semiconductor device of any in the previous claims at a frequency of at least 30 GHz.